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Amendments to the Specification

Please replace the paragraph at page 2, lines 18 through 22 with the following amended paragraph:

The present invention provides a lead-free solder composition for soldering to a glass substrate, wherein the solder composition includes tin (Sn) and silver (Ag) as well as a granular additive material having a low coefficient of thermal expansion to combat thermal shock and the percent weight of the solder and granular additive are at least can be about 97% and at least 3%, respectively.